

# Yingxin Goh

## List of Publications by Year in descending order

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Version: 2024-02-01

17  
papers

317  
citations

1307594

7  
h-index

1199594

12  
g-index

17  
all docs

17  
docs citations

17  
times ranked

292  
citing authors

#	ARTICLE	IF	CITATIONS
1	Characterization of pervious concrete with blended natural aggregate and recycled concrete aggregates. <i>Journal of Cleaner Production</i> , 2018, 181, 155-165.	9.3	112
2	Effects of hydroquinone and gelatin on the electrodeposition of Sn-Bi low temperature Pb-free solder. <i>Electrochimica Acta</i> , 2013, 90, 265-273.	5.2	61
3	Hydraulic and strength characteristics of pervious concrete containing a high volume of construction and demolition waste as aggregates. <i>Construction and Building Materials</i> , 2020, 253, 119251.	7.2	61
4	Deformation and fracture behaviour of electroplated Sn-Bi/Cu solder joints. <i>Journal of Materials Science</i> , 2015, 50, 4258-4269.	3.7	28
5	Electrodeposition of lead-free solder alloys. <i>Soldering and Surface Mount Technology</i> , 2013, 25, 76-90.	1.5	11
6	Relationship between microstructure and performance of polypropylene fibre reinforced cement composites subjected to elevated temperature. <i>European Journal of Environmental and Civil Engineering</i> , 2022, 26, 1792-1806.	2.1	9
7	Effects of alloying element on mechanical properties of Sn-Bi solder alloys: a review. <i>Soldering and Surface Mount Technology</i> , 2022, 34, 300-318.	1.5	9
8	Studies on electrodeposition behavior of Sn-Bi alloys in plating baths modified by hydroquinone and gelatin. <i>Journal of Materials Science</i> , 2016, 51, 5823-5833.	3.7	7
9	Recycling of Construction and Demolition Wastes Into Renewable Construction Materials. , 2020, , 520-526.		6
10	Formation of Sn-Bi solder alloys by sequential electrodeposition and reflow. <i>Journal of Materials Science: Materials in Electronics</i> , 2013, 24, 2052-2057.	2.2	4
11	Formation and characterization of intermetallic compounds in electroplated cobalt-tin multilayers. <i>Journal of Materials Science: Materials in Electronics</i> , 2018, 29, 5791-5798.	2.2	4
12	Growth and mechanical properties of intermetallic compound between solid cobalt and molten tin. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 4554-4562.	2.2	2
13	The Potential of Geopolymer in Development of Green Coating Materials: A Review. <i>Arabian Journal for Science and Engineering</i> , 2022, 47, 12289-12299.	3.0	2
14	Failure Mechanisms of Structural Bamboo Using Microstructural Analyses. <i>Advances in Materials Science and Engineering</i> , 2021, 2021, 1-10.	1.8	1
15	Effects of stacking sequence of electrodeposited Sn and Bi layers on reflowed Sn-Bi solder alloys. , 2012, , .		0
16	Composition estimation of Sn-Bi alloy electrodeposition using polarization curve. <i>Journal of Materials Science: Materials in Electronics</i> , 2017, 28, 11186-11191.	2.2	0
17	Formation and nanomechanical properties of intermetallic compounds in electrodeposited Cu-Sn-Co multilayers. <i>Journal of Materials Science: Materials in Electronics</i> , 2021, 32, 9490-9499.	2.2	0